

1. General description

Planar passivated Silicon Controlled Rectifier (SCR) in a SOT428 (DPAK) surface mountable plastic package intended for use in applications requiring high bidirectional blocking voltage capability, high surge current capability and high thermal cycling performance.

2. Features and benefits

- High bidirectional blocking voltage capability
- High surge current capability
- High thermal cycling performance
- Surface mountable package

3. Applications

- Ignition circuits
- Motor control
- Protection circuits
- Voltage regulation

4. Quick reference data

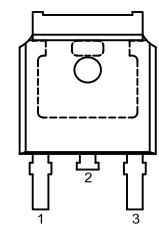
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	-	800	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 103^\circ C$; Fig. 1	-	-	7.5	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 103^\circ C$; Fig. 2 ; Fig. 3	-	-	12	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25^\circ C$; $t_p = 10 \text{ ms}$; Fig. 4 ; Fig. 5	-	-	120	A
		half sine wave; $T_{j(init)} = 25^\circ C$; $t_p = 8.3 \text{ ms}$	-	-	132	A
T_j	junction temperature		-	-	125	°C
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12 \text{ V}$; $I_T = 0.1 \text{ A}$; $T_j = 25^\circ C$; Fig. 8	-	2	15	mA
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 536 \text{ V}$; $T_j = 125^\circ C$; $R_{GK} = 100 \Omega$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; Fig. 13	200	1000	-	V/μs

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
		$V_{DM} = 536 \text{ V}$; $T_j = 125 \text{ }^\circ\text{C}$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit; Fig. 13		50	130	-	$\text{V}/\mu\text{s}$

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
3	G	gate		
mb	A	mounting base; connected to anode	 DPAK (SOT428)	

6. Ordering information

Table 3. Ordering information

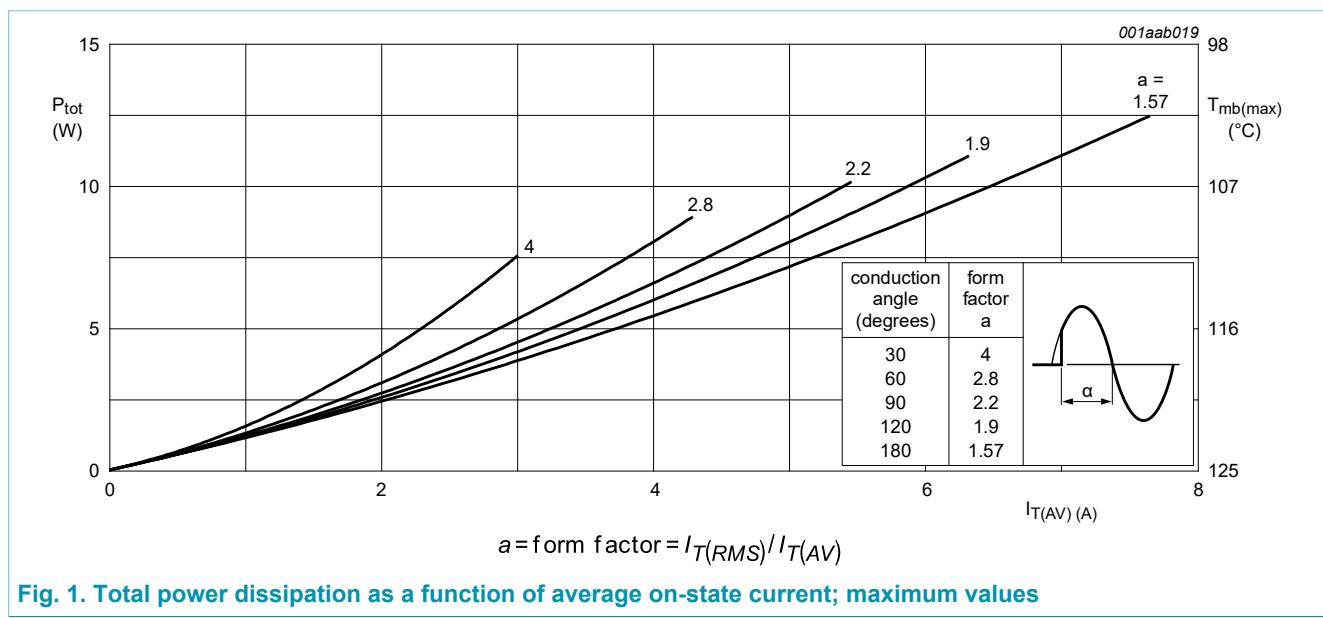
Type number	Package		
	Name	Description	Version
BT151S-800R	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	SOT428

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	800	V
V_{RRM}	repetitive peak reverse voltage		-	800	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 103^\circ\text{C}$; Fig. 1	-	7.5	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 103^\circ\text{C}$; Fig. 2 ; Fig. 3	-	12	A
	non-repetitive peak on-state current	half sine wave; $T_{j(\text{init})} = 25^\circ\text{C}$; $t_p = 10\text{ ms}$; Fig. 4 ; Fig. 5	-	120	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; SIN	-	72	A^2s
			-	50	$\text{A}/\mu\text{s}$
I_{GM}	peak gate current		-	2	A
V_{RGM}	peak reverse gate voltage		-	5	V
P_{GM}	peak gate power		-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.5	W
T_{stg}	storage temperature		-40	150	$^\circ\text{C}$
T_j	junction temperature		-	125	$^\circ\text{C}$



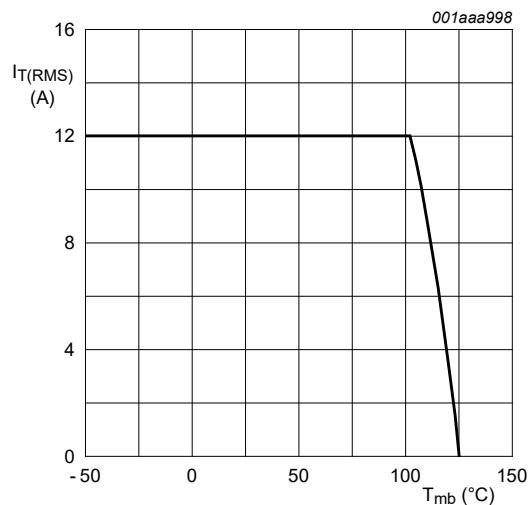
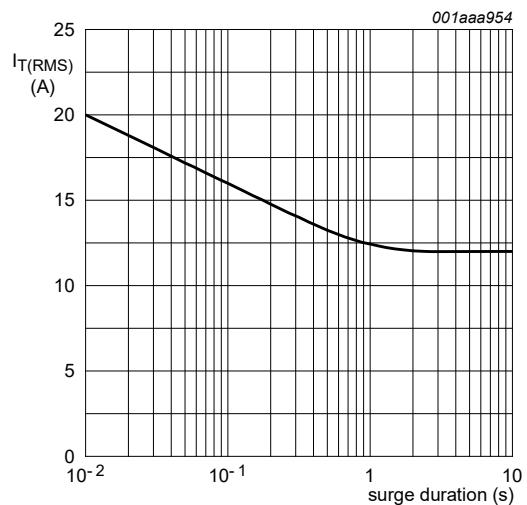


Fig. 2. RMS on-state current as a function of mounting base temperature; maximum values



f = 50 Hz; T_{mb} = 103 °C

Fig. 3. RMS on-state current as a function of surge duration; maximum values

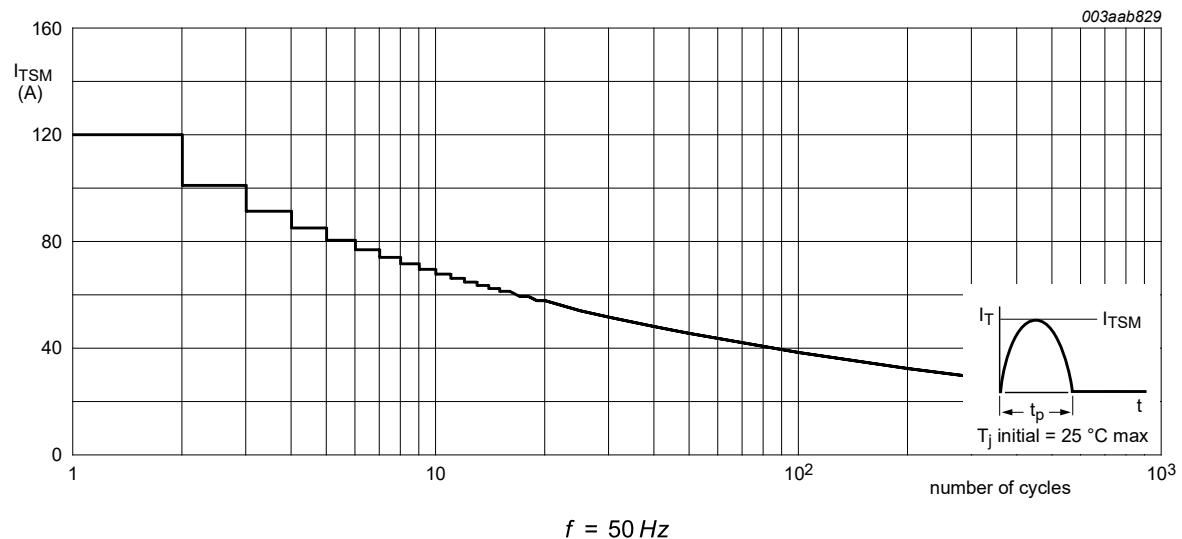


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25^\circ\text{C}$; Fig. 8		-	2	15	mA
I_L	latching current	$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_j = 25^\circ\text{C}$; Fig. 9		-	10	40	mA
I_H	holding current	$V_D = 12 \text{ V}; T_j = 25^\circ\text{C}$; Fig. 10		-	7	20	mA
V_T	on-state voltage	$I_T = 23 \text{ A}; T_j = 25^\circ\text{C}$; Fig. 11		-	1.4	1.75	V
V_{GT}	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25^\circ\text{C}$; Fig. 12		-	0.6	1.5	V
		$V_D = 800 \text{ V}; I_T = 0.1 \text{ A}; T_j = 125^\circ\text{C}$; Fig. 12		0.25	0.4	-	V
I_D	off-state current	$V_D = 800 \text{ V}; T_j = 125^\circ\text{C}$		-	0.1	0.5	mA
I_R	reverse current	$V_R = 800 \text{ V}; T_j = 125^\circ\text{C}$		-	0.1	0.5	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 536 \text{ V}; T_j = 125^\circ\text{C}; R_{GK} = 100 \Omega$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; Fig. 13		200	1000	-	V/ μ s
		$V_{DM} = 536 \text{ V}; T_j = 125^\circ\text{C}$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit; Fig. 13		50	130	-	V/ μ s
t_{gt}	gate-controlled turn-on time	$I_{TM} = 40 \text{ A}; V_D = 800 \text{ V}; I_G = 0.1 \text{ A}; dI_G/dt = 5 \text{ A}/\mu\text{s}; T_j = 25^\circ\text{C}$		-	2	-	μ s
t_q	commutated turn-off time	$V_{DM} = 536 \text{ V}; T_j = 125^\circ\text{C}; I_{TM} = 20 \text{ A}; V_R = 25 \text{ V}; (dI_T/dt)_M = 30 \text{ A}/\mu\text{s}; dV_D/dt = 50 \text{ V}/\mu\text{s}; R_{GK(ext)} = 100 \Omega$; ($V_{DM} = 67\%$ of V_{DRM})		-	70	-	μ s

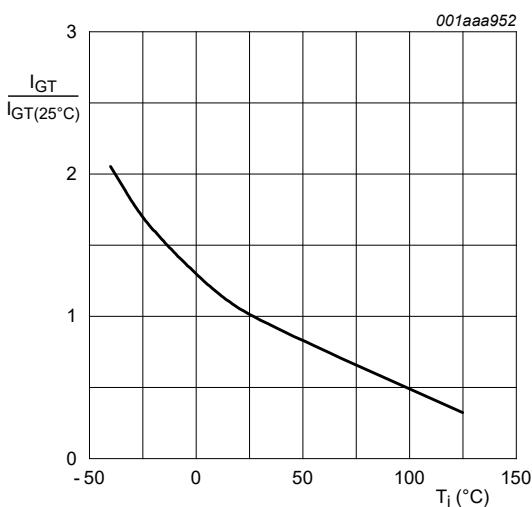


Fig. 8. Normalized gate trigger current as a function of junction temperature

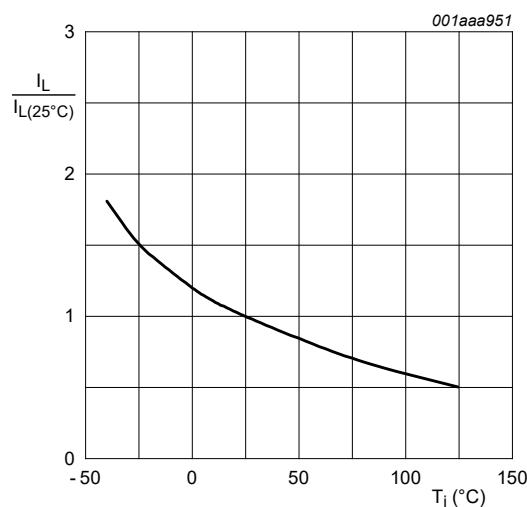


Fig. 9. Normalized latching current as a function of junction temperature

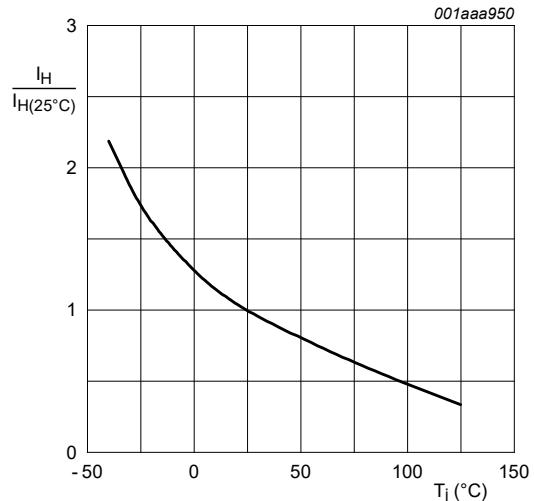
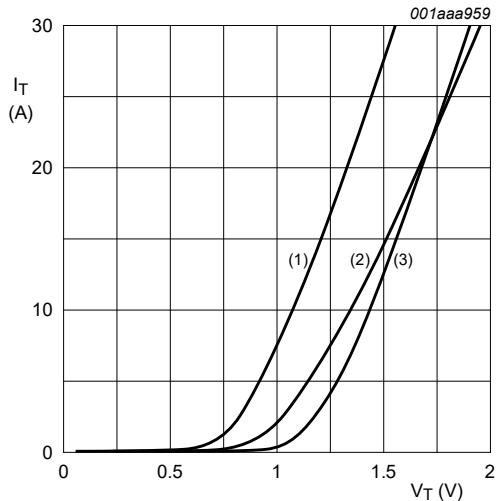


Fig. 10. Normalized holding current as a function of junction temperature



$V_o = 1.06 \text{ V}$; $R_s = 0.0304 \Omega$
 (1) $T_j = 125 \text{ }^\circ\text{C}$; typical values
 (2) $T_j = 125 \text{ }^\circ\text{C}$; maximum values
 (3) $T_j = 25 \text{ }^\circ\text{C}$; maximum values

Fig. 11. On-state current as a function of on-state voltage

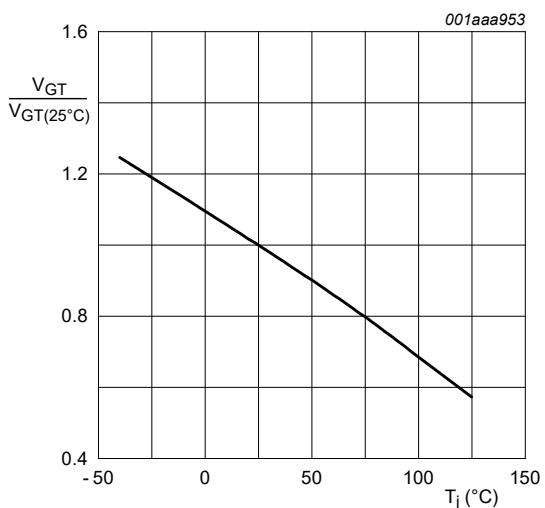


Fig. 12. Normalized gate trigger voltage as a function of junction temperature

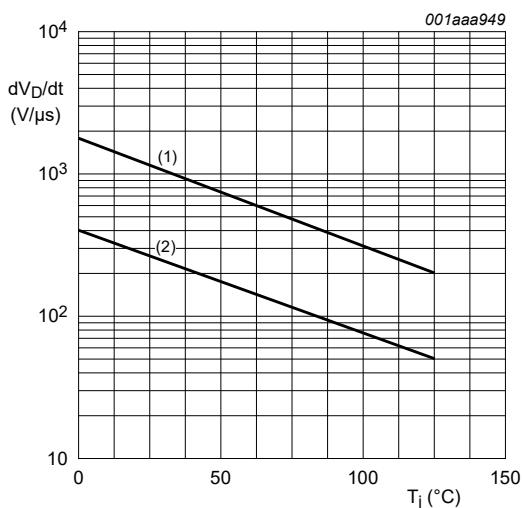


Fig. 13. Critical rate of rise of off-state voltage as a function of junction temperature; minimum values

10. Package outline

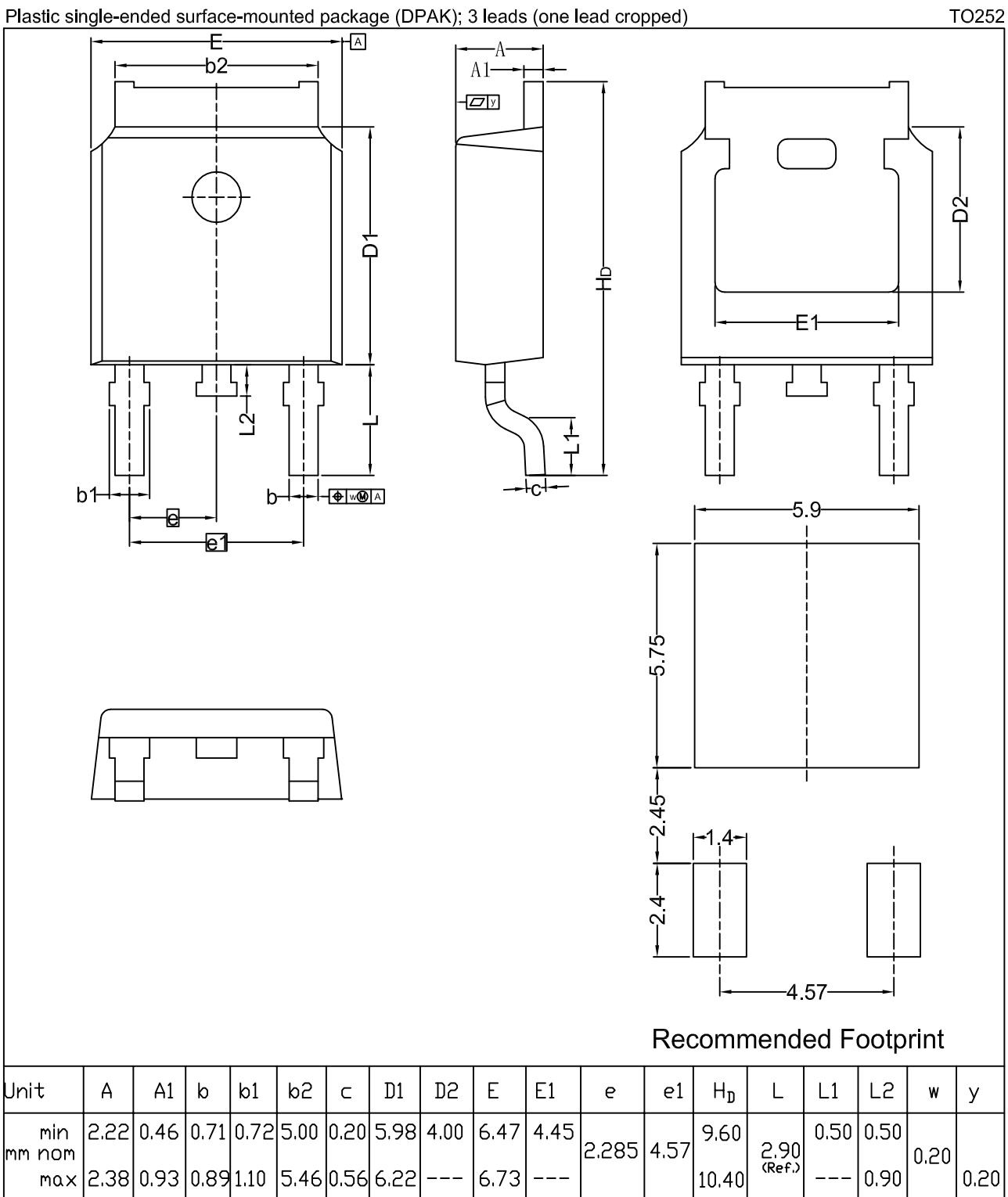


Fig. 14. Package outline DPAK (SOT428)

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